



VP800 VP800 vacuum

Vapor Phase Soldering Systems for Small Series, Prototyping and Laboratories

ASSCON vapor phase reflow soldering systems set standards in soldering technology. The VP800 series was developed for laboratory and prototyping purposes, and for small series soldering. The VP800 vacuum achieves void-free solder joints of outstanding quality. The vacuum module can be retrofitted.

EASY FLEXIBLE OPERATION

The innovative VP800 series concept enables defect free soldering of even complex SMD-Assemblies with unleaded or leaded solder paste in virtually any order. The system is particularly noted for the simplicity of its mechanical processes. The operating concept is user friendly throughout, and includes ease of maintenance.

By separating process and cooling zone, the VP800 soldering process achieves results worthy of series production facilities in a compact space. The solder material is loaded over a lock system at the front.

OPTIMUM TEMPERATURE CONTROL

The use of liquid or vapor for as a mean of energy transmission is far more effective than convection. The vapor condenses on the solder product, the condensate encapsulates it completely, and thus transmits the energy. The entire pre-heating and soldering process takes place in an oxygen-free environment. Product overheating, component damage or PCB delamination cannot occur. An optimum temperature is automatically guaranteed at all positions on the product thanks to infinite sensor-based temperature gradient controlling (deactivated in vacuum mode).

BENEFITS

- Infinitely adjustable temperature gradient with sensor-based profiling (deactivated in vacuum mode)
- oxygen-free pre-heating and soldering process
- automatic detection of the peak temperature guarantees reliable, fully completed soldering process
- leaded applications can be soldered in lead-free process environment (not in vacuum mode)
- ready for use after a short pre-heating period

voids
< 1 %

After Multi
Vacuum
treatment.

< 2 EUR

average
running
costs/h*

* System consumption data

VP800 | VP800 vacuum

Vapor Phase Soldering Systems

RANGE OF APPLICATION

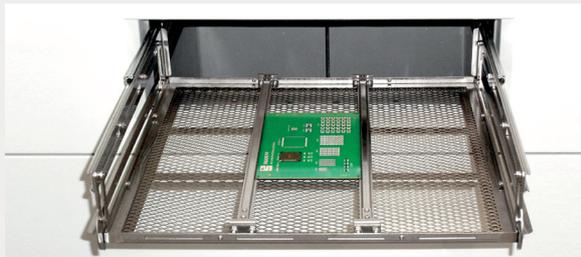
SMALL SERIES | PROTOTYPING | LABORATORY | RESEARCH AND DEVELOPMENT



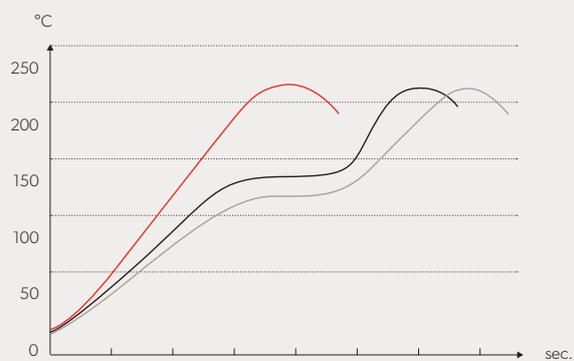
PRODUCT	VP800	VP800 VACUUM
TECHNICAL DATA		
Maximum solder product format (mm)	610 x 460	480 x 295
Supply voltage	400V/3/N/PE - 50Hz/60Hz	400V/3/N/PE - 50Hz/60Hz
Average energy consumption	1,8kWh/2,3kWh*	2,2kWh/2,7kWh*
Ready for use	ca. 30min.	ca. 60min.
Operating mode	Batch	Batch
Vacuum pump	-	0.5 mbar

SPECIAL FEATURES VP 800 VACUUM

- Variable vacuum guarantees optimum void-free solder joints
- Easy activation/deactivation of the vacuum process ensures maximum production flexibility
- The compact technical module permits space-saving assembly
- Multi Vacuum Process



The system is loaded with products over a lock at the front.



The VP800 system permits infinite adjustment of the specified temperature gradients/profiles.

* Capacity 80%/100 %

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